

SPECIFICATIONS

Middle Power LED Series
3030
LM301B Plus
CRI 75 For Domestic



Features & Benefits

- 0.3W Class middle power LED
- Mold resin for high reliability
- Standard form factor for design flexibility (3.0 × 3.0 mm)

Dongbu LED Co., Ltd.

53-24 , Dongtansandan 6-gil , Hwaseong-si , Gyeonggi-do , Republic of Korea 18487

Tel. : +82 - 70 - 8874 - 9943 Fax. : +82 - 31 - 373 - 7626

[http : //www.dongbuled-s.com](http://www.dongbuled-s.com)

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1. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	P	M	W	H	D	3	2	A	M	W	D	X	A	R	0	S	0

Digit	PKG Information	Code	Specification			
1 2 3	Dongbu Package Middle Power	SPM	Middle power			
4 5	Color	WH	White			
6	Product Version	D	Dispensing			
7 8 9	Form Factor	32A	3.0 x 3.0 x 0.75 mm 2 pads			
10	Sorting Current (mA)	M	65 mA			
11	Chromaticity Coordinates	W	ANSI Standard, MacAdam 3 step ellipse bin, MacAdam 5 step ellipse bin			
12	CRI	D	Min. 75			
13 14	Forward Voltage (V)	XA	2.6~2.9	Bin Code	AY	2.6~2.7
					AZ	2.7~2.8
					A1	2.8~2.9
15 16	CCT (K)	R0	5000	RA, RB, RC, RE, RF, RG, RH, RJ, RK, RL, RM		
		Q0	5700	QA, QB, QC, QE, QF, QG, QH, QJ, QK, QL, QM		
17 18	Luminous Flux	S0	Bin Code	SM, SN, SP		
		SM		SM		
		SN		SN		
		N8		SN, SP		
		SP		SP		

2. Characteristics

(1) Absolute Maximum Ratings

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	T_a	-40 ~ +85	°C	
Storage Temperature	T_{stg}	-40 ~ +120	°C	
LED Junction Temperature	T_j	125	°C	
Forward Current	I_F	300	mA	
Peak Pulsed Forward Current	I_{FP}	500	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260<10	°C/S	
ESD (HBM)	-	5	KV	

(2) Electro-optical Characteristics ($I_F = 65 \text{ mA}$, $T_s = 25 \text{ °C}$)

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage (VF)	V	XA	AY	2.6	-	2.7
			AZ	2.7	-	2.8
			A1	2.8	-	2.9
Reverse Voltage (@ 5 mA)	V			0.7	-	1.2
Color Rendering Index (Ra)	-			80	-	-
Thermal Resistance (junction to solder point)	°C/W			-	7.5	-
Beam Angle	°			-	120	-

* Note

Dongbu maintains measurement tolerance of: forward voltage = $\pm 0.1 \text{ V}$, luminous flux = $\pm 5 \%$, CRI = ± 3

(3) Electro-optical Characteristics ($T_s = 25 \text{ °C}$)

Item	CRI	Nominal CCT (K)	SL		SM		SN		SP		Current 65mA
			Min	Max	Min	Max	Min	Max	Min	Max	
Luminous Flux (Φ_v)		5000			40.0~42.0		42.0~44.0		44.0~46.0		
		5700			39.5~42.0		42.0~44.0		44.0~46.0		

* Note

Dongbu maintains measurement tolerance of: forward voltage = $\pm 0.1 \text{ V}$, luminous flux = $\pm 5 \%$, CRI = ± 3

(4) Luminous Flux Bins ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)

CRI (Ra) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ_v , lm)
75	5000	SPMWH32AMWDXAR0S0	SM	40.0 ~ 42.0
			SN	42.0 ~ 44.0
			SP	44.0 ~ 46.0
		SPMWH32AMWDXAR0N8	SN	42.0 ~ 44.0
			SP	44.0 ~ 46.0
		SPMWH32AMWDXAR0SP	SP	44.0 ~ 46.0
	5700	SPMWH32AMWDXAR0S0	SM	39.5 ~ 42.0
			SN	42.0 ~ 44.0
			SP	44.0 ~ 46.0
		SPMWH32AMWDXAR0N8	SN	42.0 ~ 44.0
			SP	44.0 ~ 46.0
		SPMWH32AMWDXAR0SP	SP	44.0 ~ 46.0

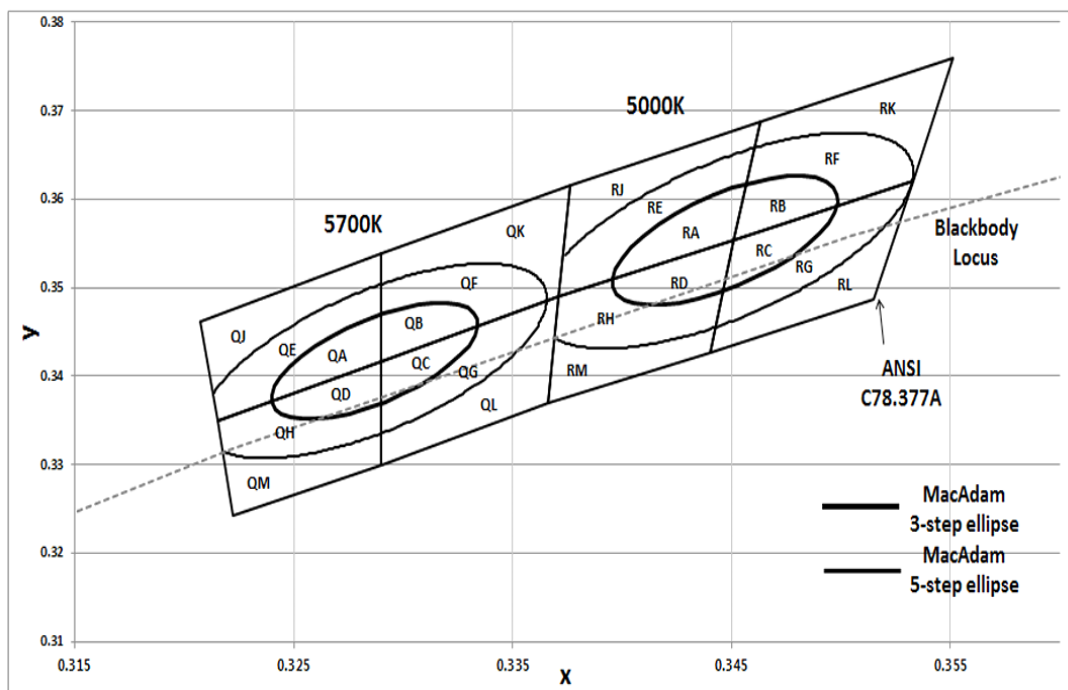
(5) Color Bins ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)

CRI (Ra) Min.	Normal CCT (K)	Product Code	Color Rank	Chromaticity Bins
75	5000	SPMWH32AMWDXAR0S0	R0 (Whole bin)	RA, RB, RC, RD, RE, RF, RG, RH, RJ, RK, RL, RM
		SPMWH32AMWDXAR0N8		
		SPMWH32AMWDXAR0SP		
	5700	SPMWH32AMWDXAQ0S0	Q0 (Whole bin)	QA, QB, QC, QD, QE, QF, QG, QH, QJ, QK, QL, QM
		SPMWH32AMWDXAQ0N8		
		SPMWH32AMWDXAQ0SP		

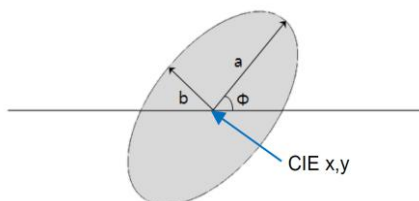
(6) Voltage Bins ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)

CRI (Ra) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
75	-	-	XA	AY	2.6 ~ 2.7
				AZ	2.7 ~ 2.8
				A1	2.8 ~ 2.9

(7) Chromaticity Region & Coordinates ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)



(8) Chromaticity Region & Coordinates ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)

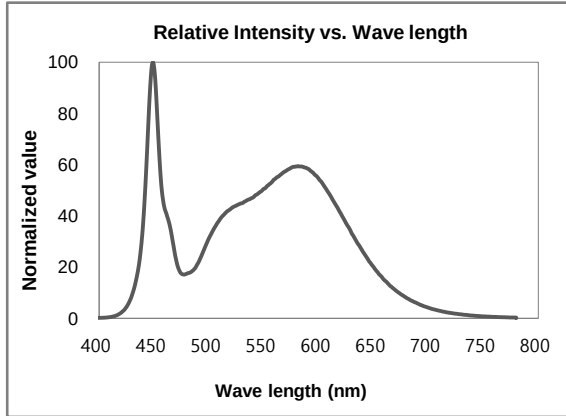


MacAdam Ellipse (R3, R5)						MacAdam Ellipse (Q3, Q5)					
Step	CIE x	CIE y	θ	a	b	Step	CIE x	CIE y	θ	a	b
3-Step	0.3447	0.3553	59.62	0.00820	0.00350	3-Step	0.3287	0.3417	59.09	0.00746	0.00320
5-Step	0.3447	0.3553	59.62	0.01370	0.00590	5-Step	0.3287	0.3417	59.09	0.01243	0.00533

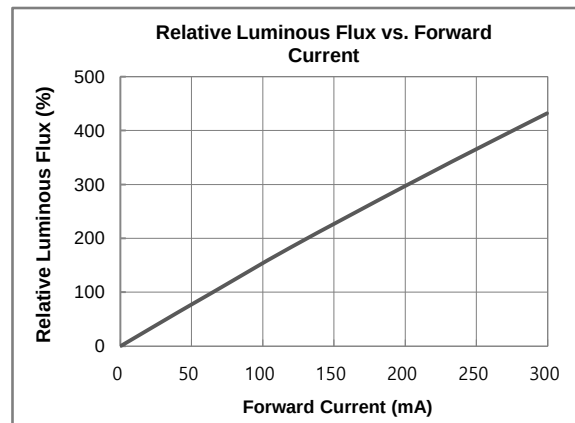
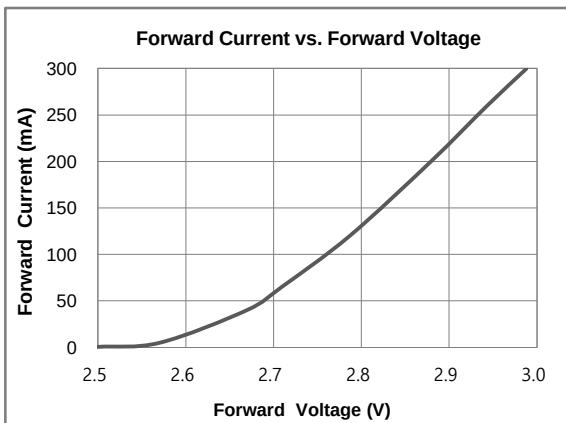
3. Typical Characteristics Graphs

(1) Spectrum Distribution ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)

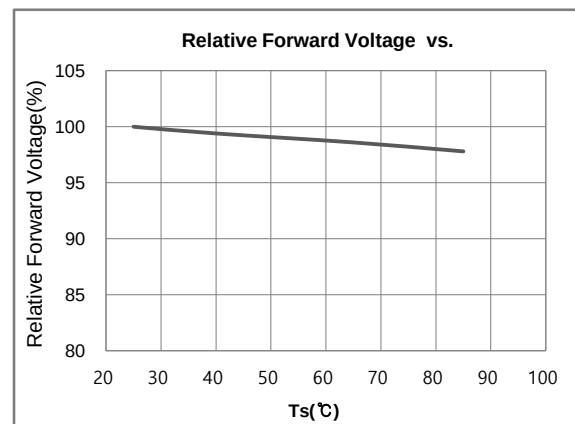
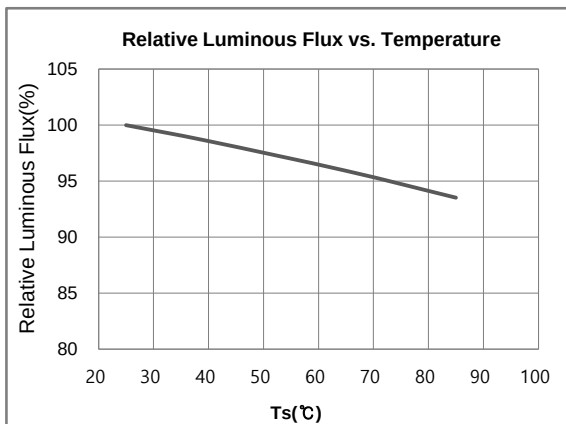
CCT : 5000 K (75 CRI)



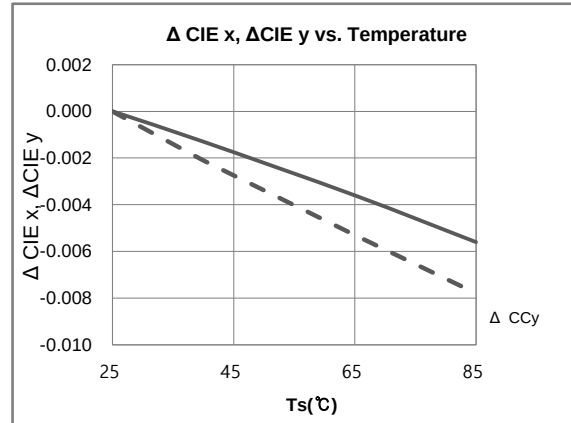
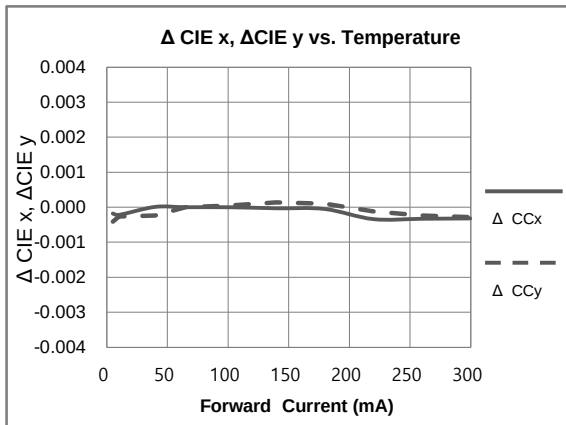
(2) Forward Current Characteristics ($T_s = 25^\circ\text{C}$)



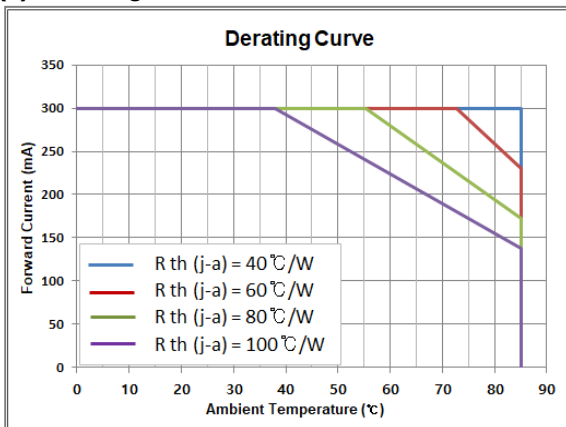
(3) Temperature Characteristics ($I_F = 65 \text{ mA}$)



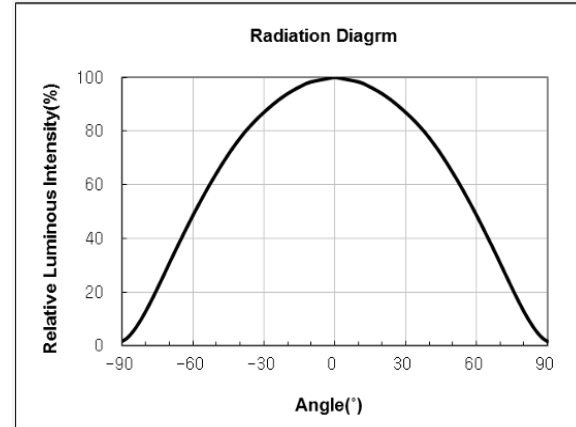
(4) Color Shift Characteristics ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)



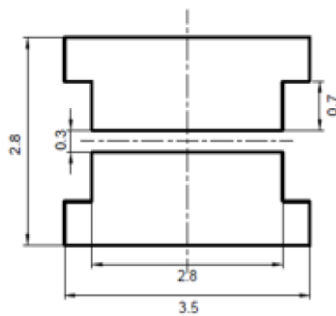
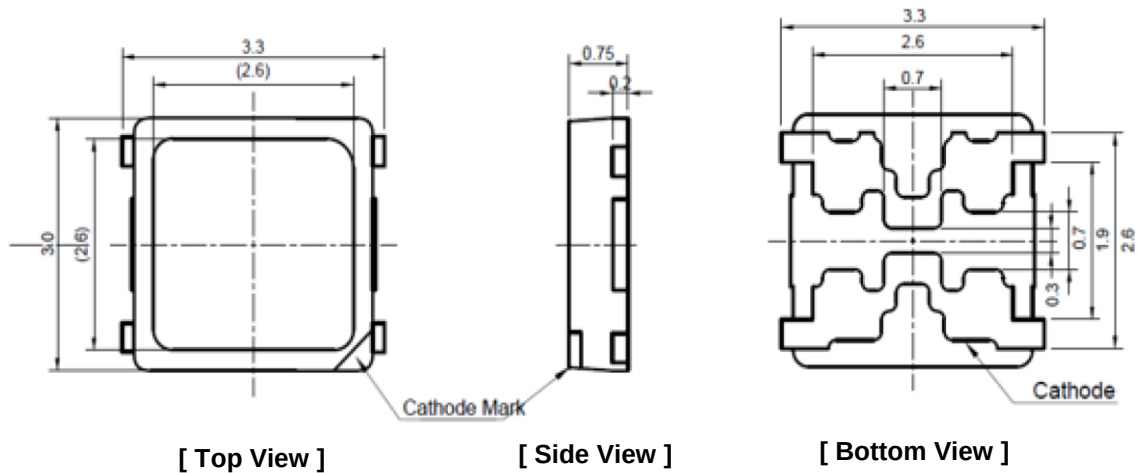
(4) Derating Curve



(6) Beam Angle Characteristics ($I_F=65 \text{ mA}$, $T_s=25^\circ\text{C}$)



4. Outline Drawing & Dimension



- Measurement unit : mm
- Tolerance : $\pm 0.1\text{mm}$

[Recommended PCB Solder Pad]

* Note :

- 1) This LED has built-in ESD protection device(s) connected in parallel to LED chip(s).
- 2) T_s point and measurement method:
 - ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach T_s point.
 - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged

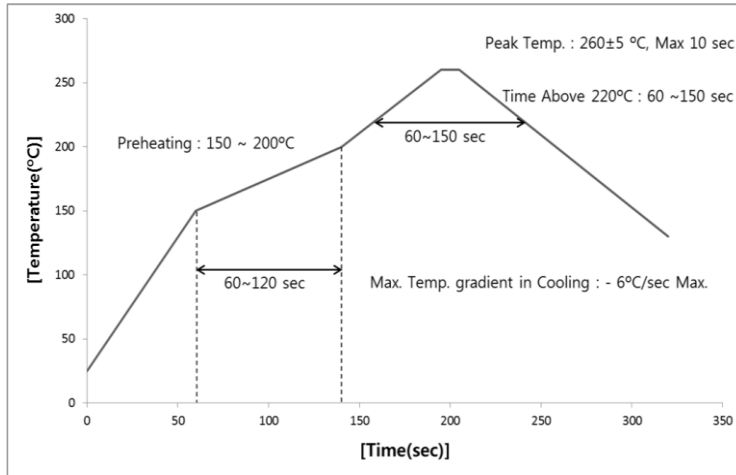
Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs.
Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

5. Soldering Conditions

(1) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



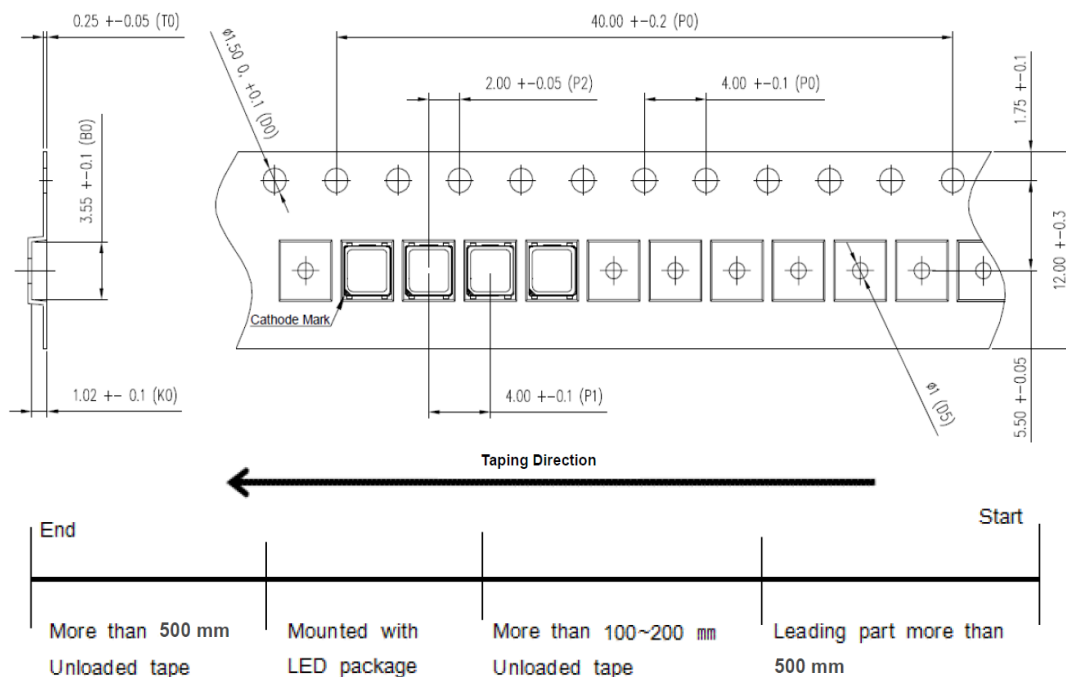
(2) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.

6. Tape & Reel

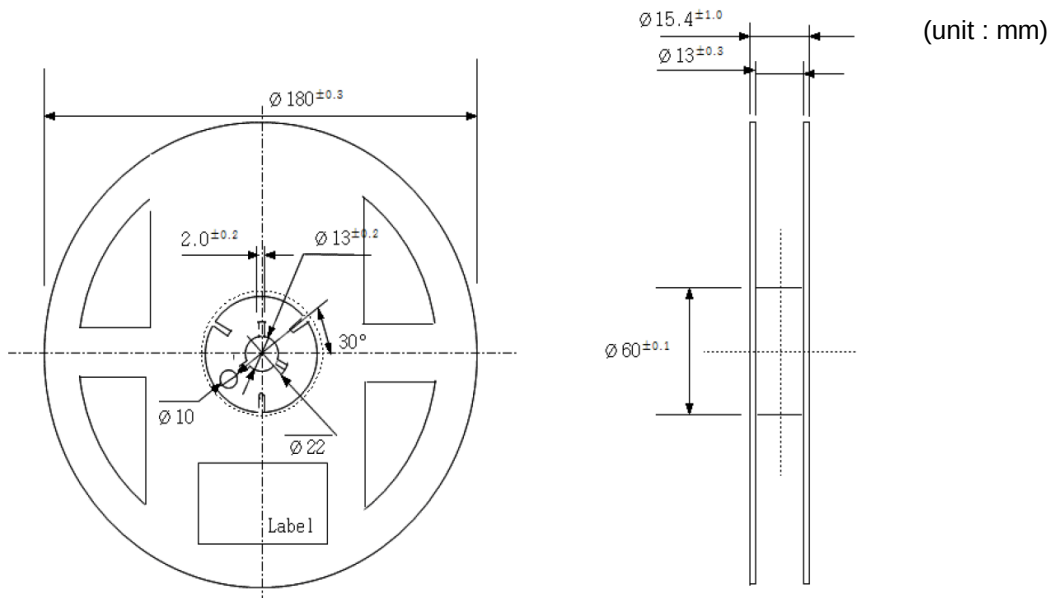
(1) Taping Dimension

(unit : mm)



6. Tape & Reel

(2) Reel Dimension (Max 4,000 pcs)

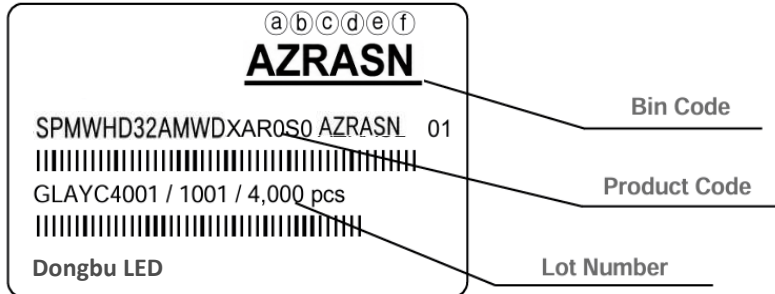


* Note :

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is ± 0.2 mm
- 3) Adhesion Strength of Cover Tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at 10° angle to the carrier tape
- 4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

7. Label Structure

(1) Label Structure



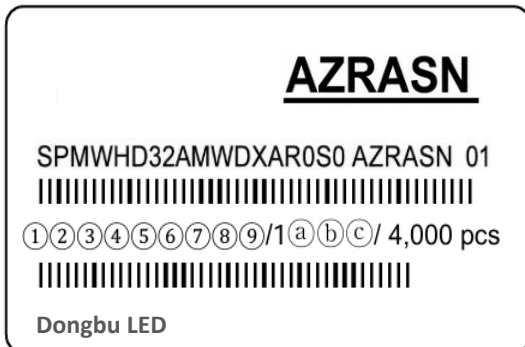
*** Note : Denoted bin code and product code above is only an example (see description on page 3)**

Bin Code

- a b**: Forward Voltage bin (refer to page 6)
- c d**: Chromaticity bin (refer to page 6)
- e f**: Luminous Flux bin (refer to page 4, 5)

(2) Lot Number

The lot number is composed of the following characters:



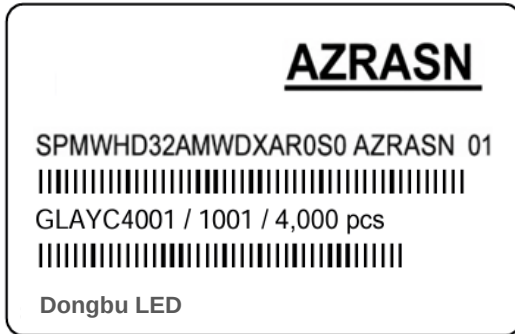
① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ / 1 a b c / 4,000 pcs

- ① ② : Production site (G4: Guangzhou, China)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (C: 2018, D: 2019, E: 2020, F: 2021, G: 2022...)
- ⑤ : Month (1~9, A, B, C)
- ⑥ : Day (1~9, A, B~V)
- ⑦ ⑧ ⑨ : Serial number (001 ~ 999)
- a b c : Reel number (001 ~ 999)

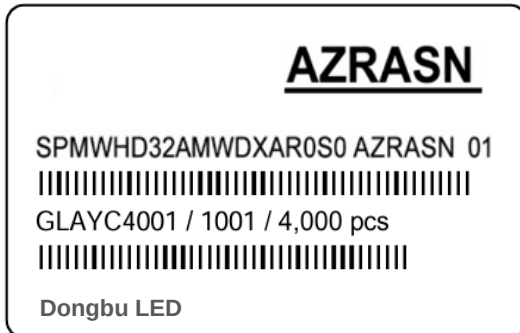
8. Packing Structure

(1) Packing Process (The quantity of PKG on the Reel to be Max 4,000 pcs)

Reel



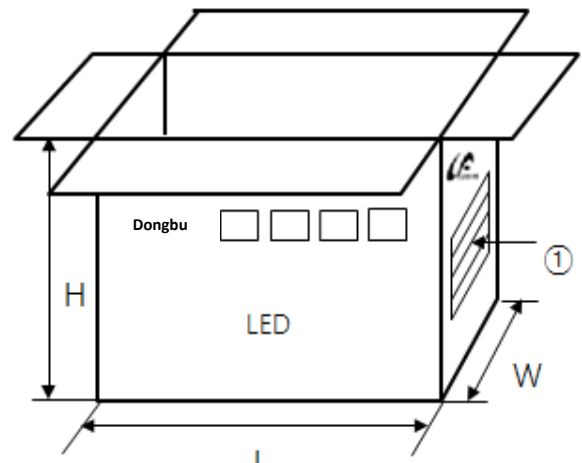
Aluminum Vinyl Packing Bag



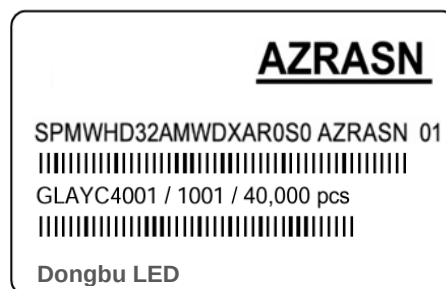
Outer Box

Material: Paper (SW3B(B))

Type	Size (mm)			Note
	L	W	H	
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels
7 inch S	245 ± 5	220 ± 5	86 ± 5	Up to 5 reels



① Side Label



8. Packing Structure

(5) Aluminum Vinyl Packing Bag



(6) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag

(This image is for reference only. Silica gel and humidity indicator shapes may be different.)



9. Precautions in Handling & Use

- (1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- (2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- (3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- (4) LEDs must be stored in a clean environment.
(shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- (5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH*^{Note 1}, or
 - b. Mounted within 24 hours (1 day) at an assembly line with a condition of more than 30 °C / 70 % RH*^{Note 2}, or
 - c. Stored at <10 % RH

*Note 1, 2: IPC/JEDEC J-STD-033A, Recommended Equivalent Total Floor Life Table

Package Type and Body Thickness	Moisture Sensitivity Level	Maximum Percent Relative Humidity						Temperature
		40%	50%	60%	70%	80%	90%	
Body Thickness <2.1mm	Level2a	∞	∞	28	1	1	1	30°C
		∞	∞	∞	2	1	1	25°C
		∞	∞	∞	2	2	1	20°C

- (6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- (7) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- (8) Devices must be baked for 10~24 hours at 60 ± 5 °C, if baking is required.
- (9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- (10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.

9. Precautions in Handling & Use

(11) Risk of sulfurization (or tarnishing)

The LED from Dongbu uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.